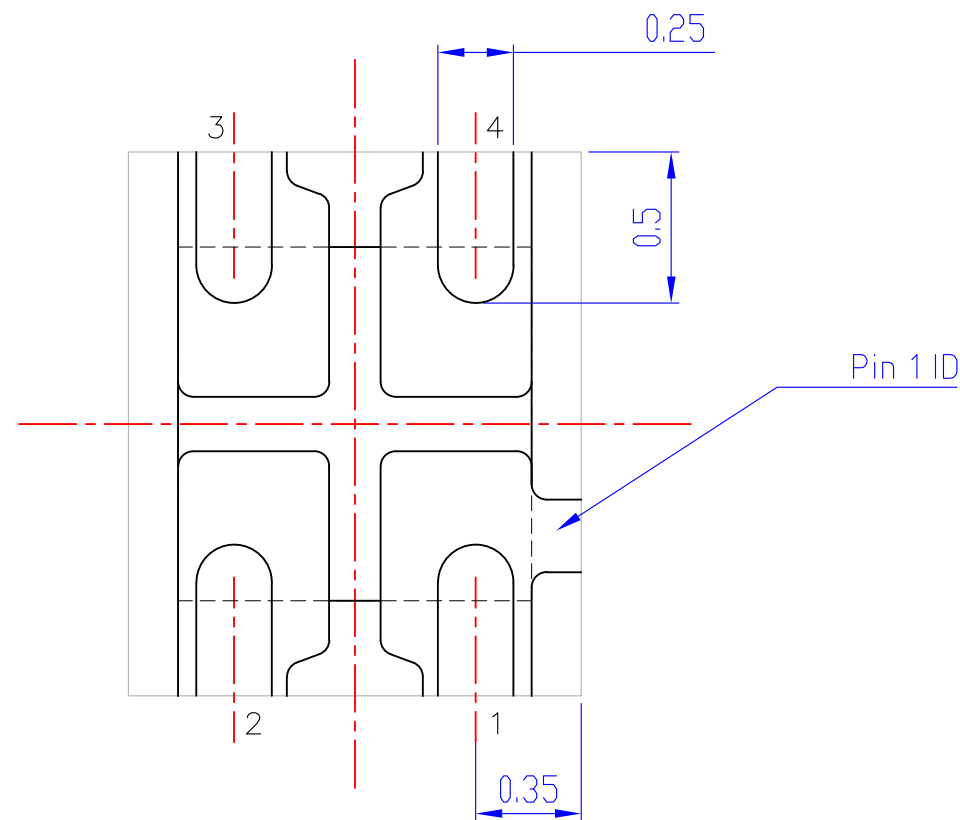
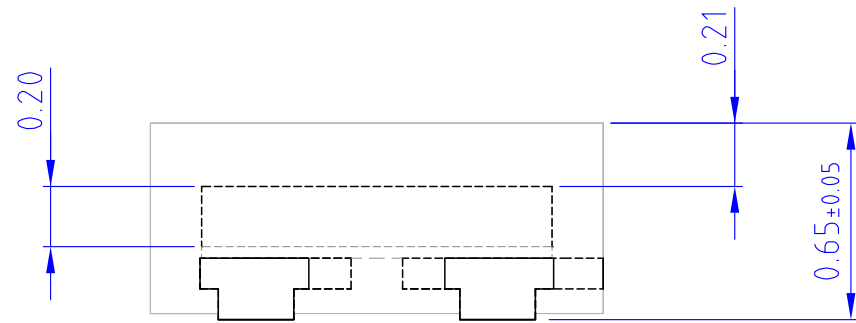


| Pin Assignments |             |
|-----------------|-------------|
| Pin #           | Description |
| 1               | Anode       |
| 2               | Fast Output |
| 3               | Cathode     |
| 4               | No Connect  |

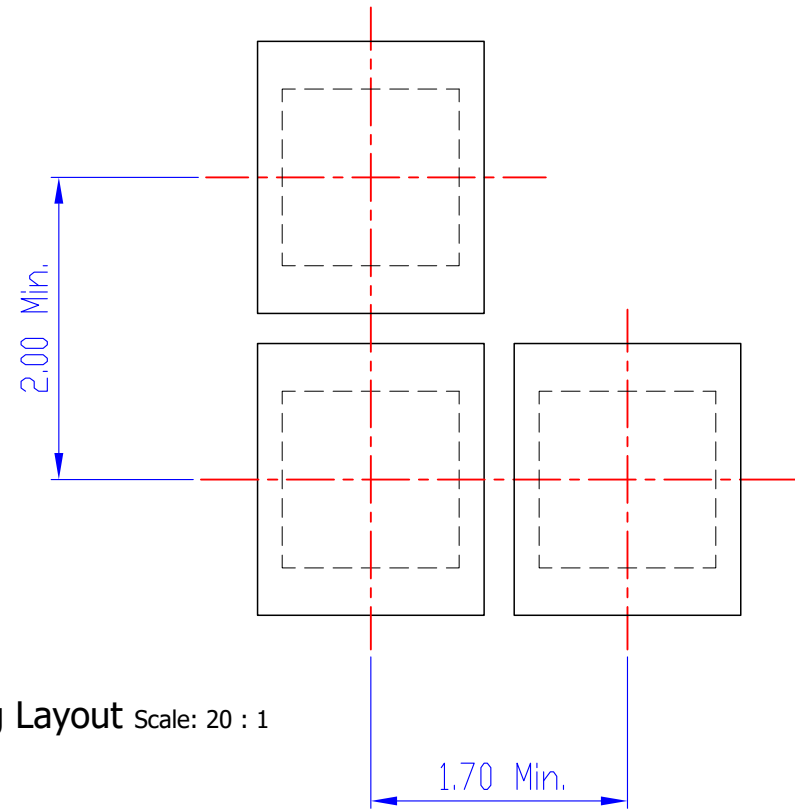
|                        |             |                                   |   |       |        |
|------------------------|-------------|-----------------------------------|---|-------|--------|
| DATE                   | 25 Oct 2016 | REVISION                          | D | SCALE | 40 : 1 |
| SensL Technologies Ltd |             |                                   |   |       | Sheet  |
| www.sensl.com          |             |                                   |   |       | 1 of 6 |
| DWG. NO:               | SND0172     | DO NOT SCALE ALL DIMENSIONS IN MM |   |       |        |
| TITLE:                 |             |                                   |   |       |        |
| MicroFC-100xx-SMT-C1   |             |                                   |   |       |        |
| PROJECTION:            |             |                                   |   |       |        |



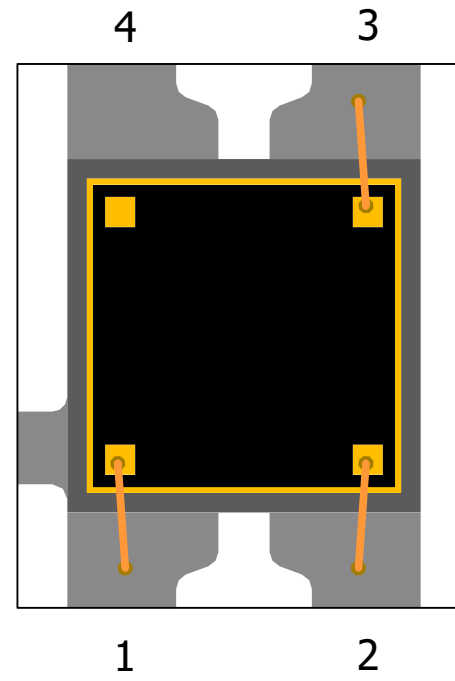
Bottom View Scale: 40 : 1

| Pin Assignments |             |
|-----------------|-------------|
| Pin #           | Description |
| 1               | Anode       |
| 2               | Fast Output |
| 3               | Cathode     |
| 4               | No Connect  |

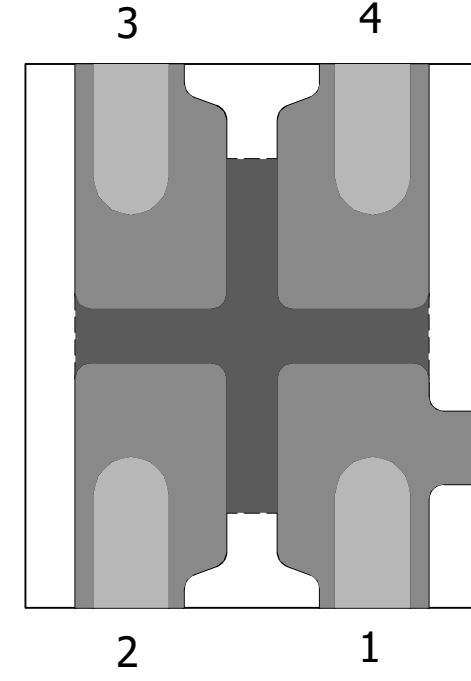
|                        |             |              |                      |        |        |
|------------------------|-------------|--------------|----------------------|--------|--------|
| DATE                   | 25 Oct 2016 | REVISION     | D                    | SCALE: | 40 : 1 |
| SensL Technologies Ltd |             |              |                      |        | Sheet  |
| www.sensl.com          |             |              |                      |        | 2 of 6 |
| DWG. NO:               | SND0172     | DO NOT SCALE | ALL DIMENSIONS IN MM |        |        |
| TITLE:                 |             |              |                      |        |        |
| MicroFC-100xx-SMT-C1   |             |              |                      |        |        |
| PROJECTION:            |             |              |                      |        |        |



Tiling Layout Scale: 20 : 1



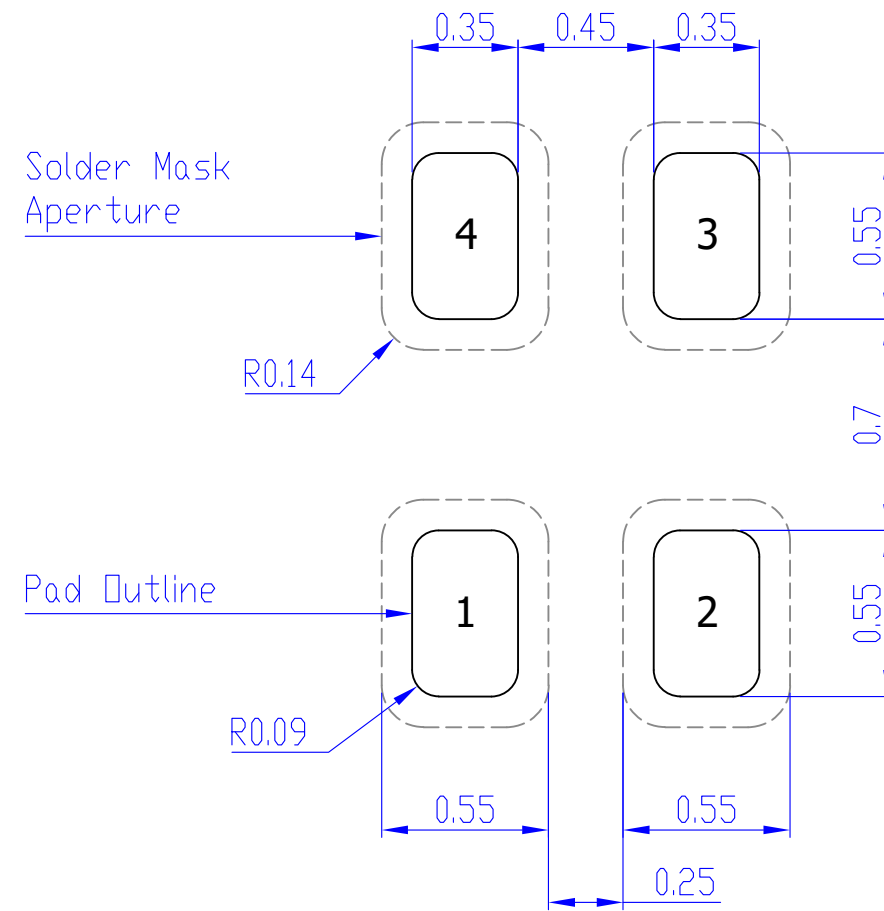
Top View Scale: 40 : 1



Bottom View Scale: 40 : 1

NOTE: Alignment and placement tolerances depend on the accuracy of the equipment used in the assembly process.

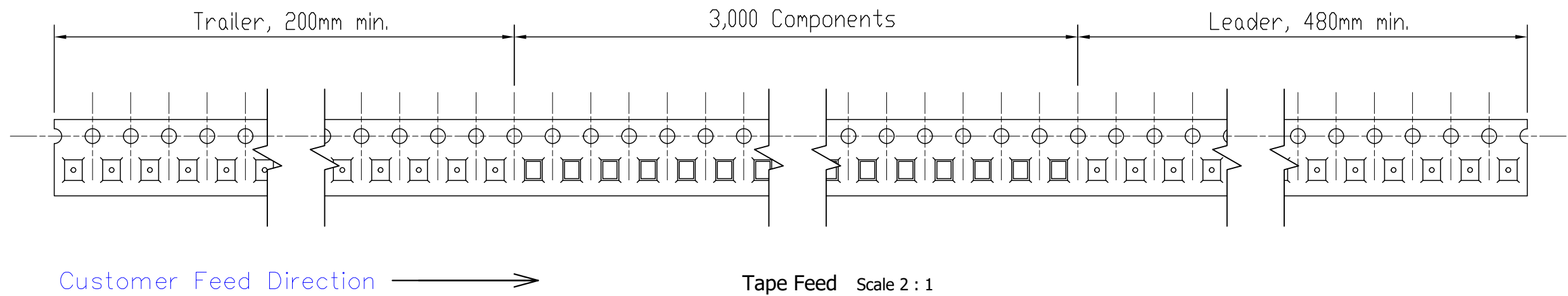
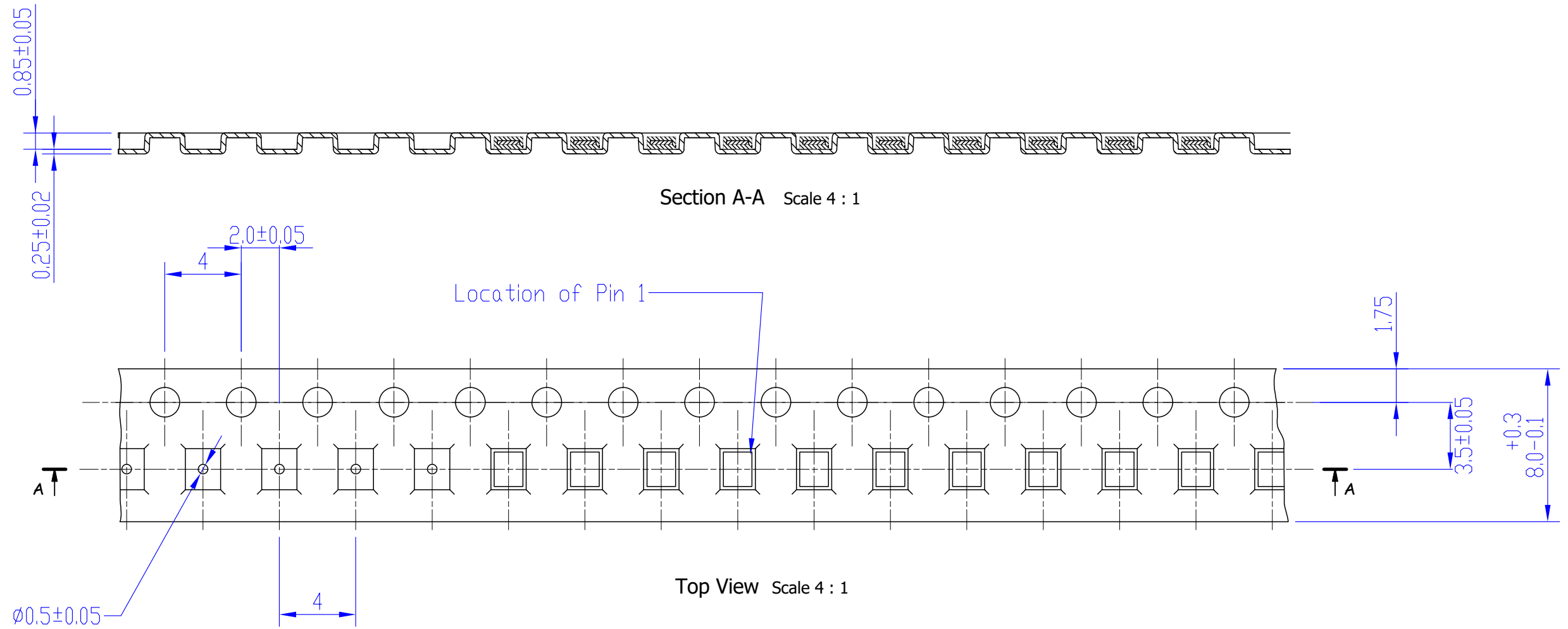
|                        |             |              |                      |        |        |
|------------------------|-------------|--------------|----------------------|--------|--------|
| DATE                   | 25 Oct 2016 | REVISION     | D                    | SCALE: | 20 : 1 |
| SensL Technologies Ltd |             |              |                      |        | Sheet  |
| www.sensl.com          |             |              |                      |        | 3 of 6 |
| DWG. NO:               | SND0172     | DO NOT SCALE | ALL DIMENSIONS IN MM |        |        |
| TITLE:                 |             |              |                      |        |        |
| MicroFC-100xx-SMT-C1   |             |              |                      |        |        |
| PROJECTION:            |             |              |                      |        |        |



Recommended PCB Solder Footprint  
Scale: 40 : 1

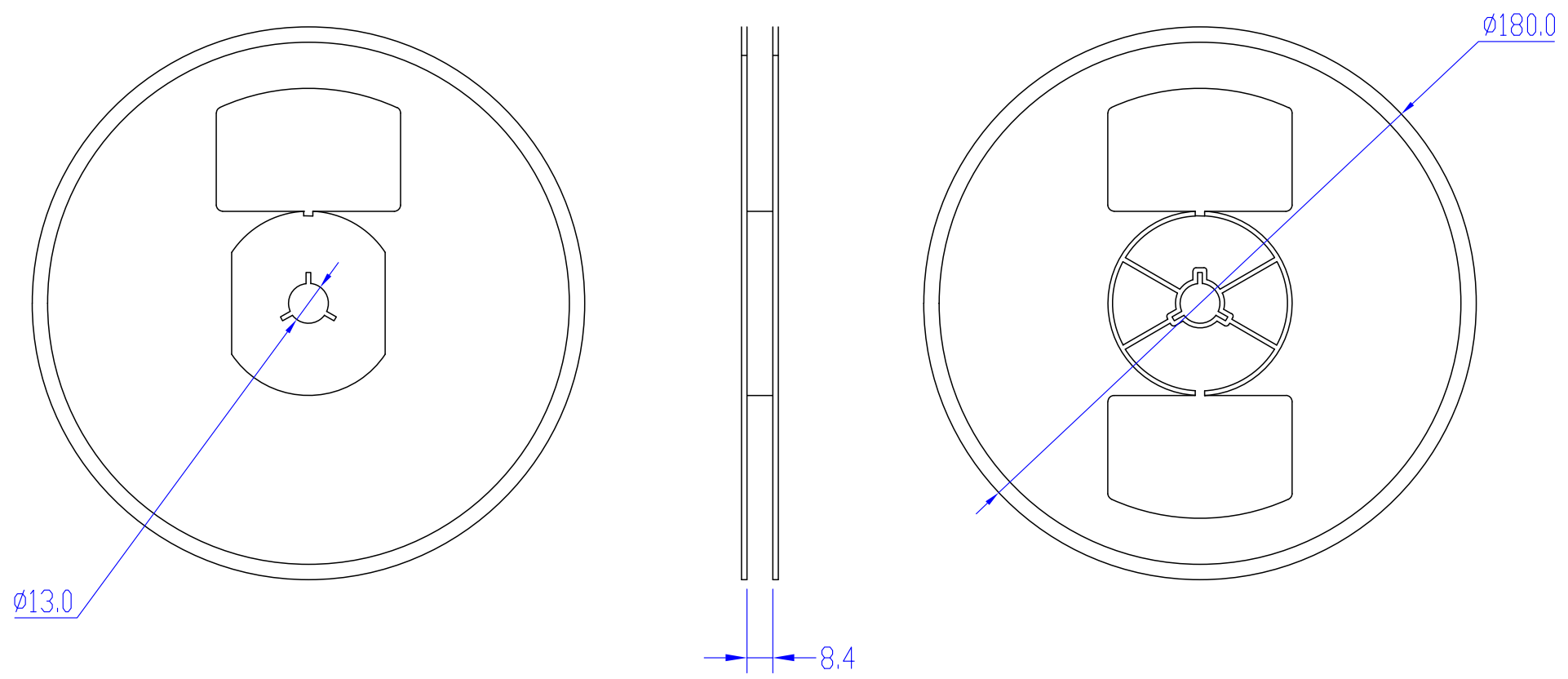
NOTE: No Connect (NC) pin 4 should be soldered to PCB, this pin can be connected to ground but it can also be left floating without affecting the dark noise.

|   |             |              |                      |        |                 |
|---|-------------|--------------|----------------------|--------|-----------------|
| DATE                                    | 25 Oct 2016 | REVISION     | D                    | SCALE: | 40 : 1          |
| SensL Technologies Ltd<br>www.sensl.com |             |              |                      |        | Sheet<br>4 of 6 |
| DWG. NO:                                | SND0172     | DO NOT SCALE | ALL DIMENSIONS IN MM |        |                 |
| TITLE:<br><b>MicroFC-100xx-SMT-C1</b>   |             |              |                      |        |                 |
| PROJECTION:                             |             |              |                      |        |                 |



All Dimensions  $\pm 0.1\text{mm}$  Unless Otherwise Stated

|                        |             |              |                      |       |        |
|------------------------|-------------|--------------|----------------------|-------|--------|
| DATE                   | 25 Oct 2016 | REVISION     | D                    | SCALE | Shown  |
| SensL Technologies Ltd |             |              |                      |       | Sheet  |
| www.sensl.com          |             |              |                      |       | 5 of 6 |
| DWG. NO:               | SND0172     | DO NOT SCALE | ALL DIMENSIONS IN MM |       |        |
| TITLE:                 |             |              |                      |       |        |
| MicroFC-100xx-SMT-C1   |             |              |                      |       |        |
| PROJECTION:            |             |              |                      |       |        |



Details of Packaging Reel Scale 1 : 2

**CAUTION**

3

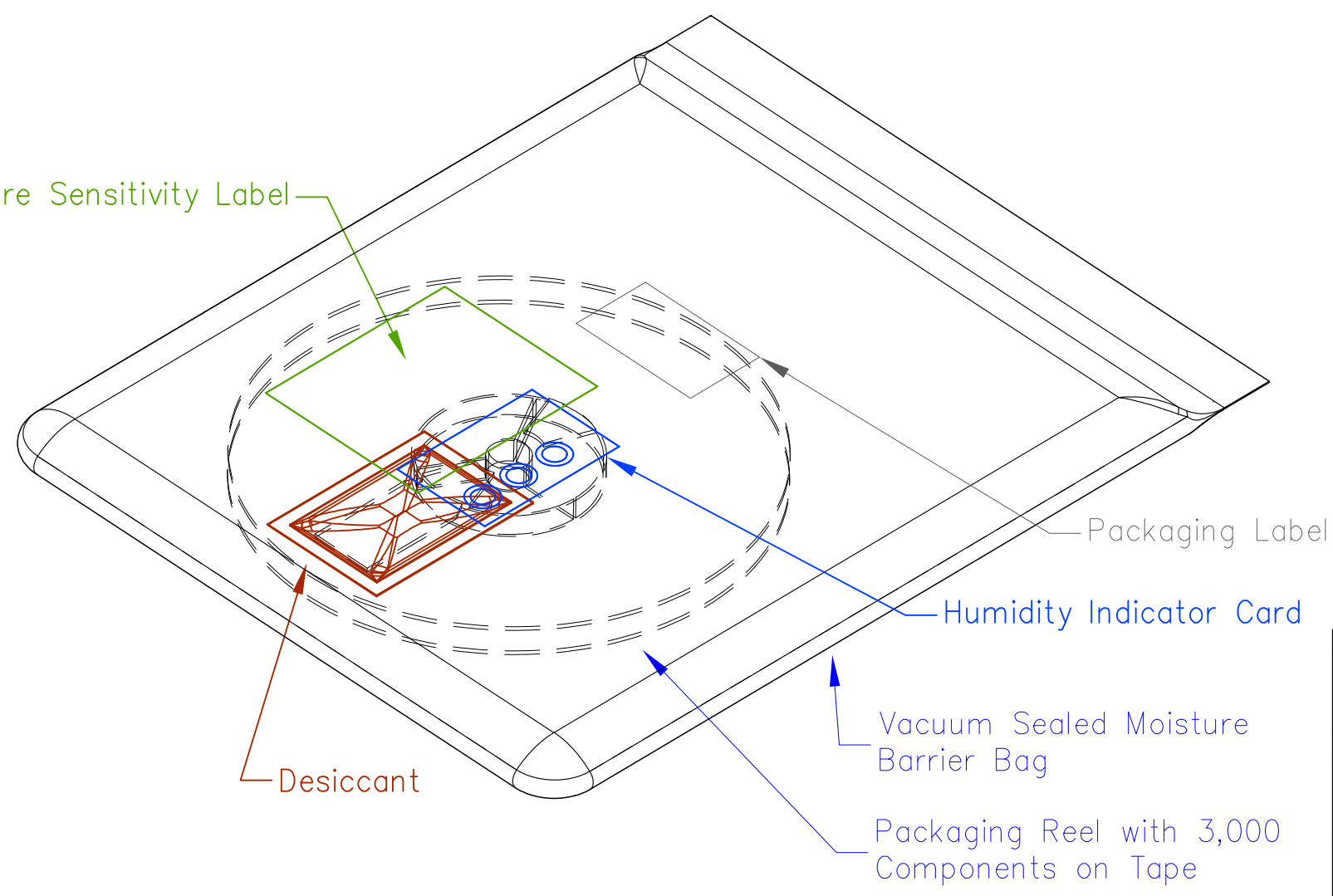
**MOISTURE SENSITIVE DEVICES**

1. Calculated shelf life in sealed bag: 24 months at <math>\le 40^{\circ}\text{C}</math> and <math>\le 90\%</math> relative humidity (RH)
2. Peak package body temperature: 260 °C  
if blank, see adjacent bar code label
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
  - a) Mounted within: 168 hours of factory conditions <math>\le 30^{\circ}\text{C}</math> <math>60\%</math> RH, or
  - b) Stored per J-STD-033
4. Devices require bake, before mounting, if:
  - a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at   - b) 3a or 3b are not met
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure

Bag Seal Date: 20 Mar. 2014  
if blank, see adjacent bar code label

Note: Level and body temperature defined by IPC/JEDEC J-STD-020

Details of Moisture Sensitivity Label



5%

10%

60%

**LEVEL2A-5A PARTS**  
Bake if 10% IS NO BROWN and 5% IS AZURE  
**DOU YEE ENTERPRISES**  
**BROWN-DRY AXURE-WET**  
COBALT FREE HUMIDITY INDICATOR CARD  
AVOID METAL CONTACT  
COMPLIES WITH IPC/JEDEC J-STD-033

**LEVEL2 PARTS**  
Bake Parts if 60% IS NO BROWN  
Initial Usage: DO NOT put this card into a bag if 5%, 10% or 60% dot are azure

H16 5 4 3 2 1

Humidity Indicator Card

sensl

sense light

**Part#: MICROFC-10035-SMT**

**Revision: C1**

**Lot#: E1234-35**

**Lot#**

**Quantity: 3000**

Sample Packaging Label

|                        |             |              |                      |        |        |
|------------------------|-------------|--------------|----------------------|--------|--------|
| DATE                   | 25 Oct 2016 | REVISION     | D                    | SCALE: | Shown  |
| SensL Technologies Ltd |             |              |                      |        | Sheet  |
| www.sensl.com          |             |              |                      |        | 6 of 6 |
| DWG. NO:               | SND0172     | DO NOT SCALE | ALL DIMENSIONS IN MM |        |        |
| TITLE:                 |             |              |                      |        |        |
| MicroFC-100xx-SMT-C1   |             |              |                      |        |        |
| PROJECTION:            |             |              |                      |        |        |